

Attorney Docket No.: CPAC 1001-1 US
USSN 09/802,443



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Linda Shaw
Linda Shaw

May 10, 2002
Date

MAY 31 2002
TECHNOLOGY CENTER 2800

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of)
Rajendra D. Pendse *et al.*)
) Examiner: Unknown
Application No.: 09/802,443)
) Group Art Unit: 2811
Filed: March 9, 2001)
) Date: May 10, 2002
Title: **Flip chip-in-leadframe**)
 package and process)
)

SEPARATE LETTER TO OFFICIAL DRAFTSPERSON

Official Draftsperson
Commissioner Of Patents
Washington, D.C. 20231

Official Draftsperson:

In connection with the above-referenced U. S. patent application, transmitted herewith are the following papers:

[X] Two (2) sheets of formal drawing(s) (Figs 1, 2, 3, 4, 5, and 6).

Authorization is hereby given to deduct from or credit to Deposit Account No. 50-0869 (CPAC 1001-1 US), any fees that may be required with this matter. A duplicate of this paper is enclosed.

Respectfully submitted,

Bill Kennedy Reg. No. 33,407
Bill Kennedy
Registration No. 33,407

Date: May 10, 2002
Haynes Beffel & Wolfeld LLP
P.O. Box 366
Half Moon Bay, CA 94019
(650) 712-0340